

**Lyontek Inc.****LY612568**

Preliminary 0.2

5V 256K X 8 BIT HIGH SPEED CMOS SRAM

REVISION HISTORY

<u>Revision</u>	<u>Description</u>	<u>Issue Date</u>
Rev. 0.1	Preliminary	Dec.6.2006
Rev. 0.2	Revised Test Condition of I_{SB1}/I_{DR} Revised V_{TERM} to V_{T1} and V_{T2} Revised <u>FEATURES & ORDERING INFORMATION</u> <u>Lead free and green package available</u> to <u>Green package available</u> Added packing type in <u>ORDERING INFORMATION</u> Deleted T_{SOLDER} in <u>ABSOLUTE MAXIMUM RATINGS</u> Revised <u>PACKAGE OUTLINE DIMENSION</u>	Aug.26.2009



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FEATURES

- Fast access time : 15/20/25ns
- Low power consumption:
Operating current: 100/80/75mA (TYP.)
Standby current: 100 μ A (TYP.)
- Single 5V power supply
- All inputs and outputs TTL compatible
- Fully static operation
- Tri-state output
- Data retention voltage : 2.0V (MIN.)
- **Green package available**
- Package : 44-pin 400 mil TSOP-II

GENERAL DESCRIPTION

The LY612568 is a 2,097,152-bit low power CMOS static random access memory organized as 262,144 words by 8 bits. It is fabricated using very high performance, high reliability CMOS technology. Its standby current is stable within the range of operating temperature.

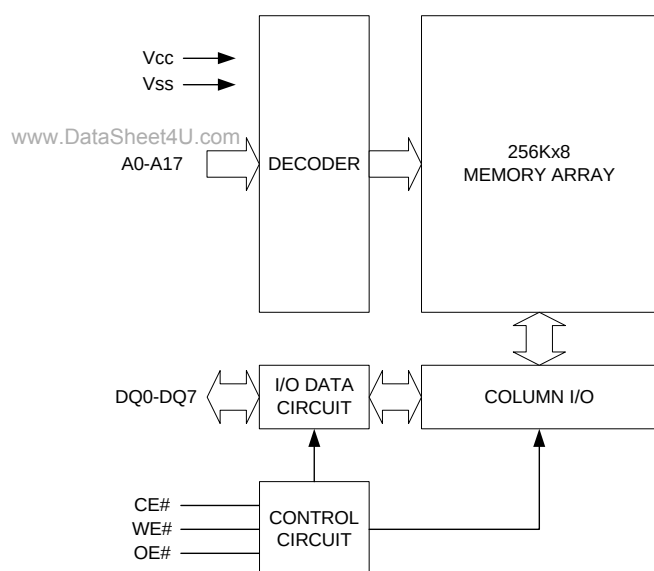
The LY612568 is well designed for low power application, and particularly well suited for battery back-up nonvolatile memory application.

The LY612568 operates from a single power supply of 5V and all inputs and outputs are fully TTL compatible

PRODUCT FAMILY

Product Family	Operating Temperature	Vcc Range	Speed	Power Dissipation	
				Standby(I _{SB1} ,TYP.)	Operating(I _{CC} ,TYP.)
LY612568	0 ~ 70°C	4.5 ~ 5.5V	15/20/25ns	100 μ A	100/80/75mA
LY612568(E)	-20 ~ 80°C	4.5 ~ 5.5V	15/20/25ns	100 μ A	100/80/75mA
LY612568(I)	-40 ~ 85°C	4.5 ~ 5.5V	15/20/25ns	100 μ A	100/80/75mA

FUNCTIONAL BLOCK DIAGRAM



PIN DESCRIPTION

SYMBOL	DESCRIPTION
A0 - A17	Address Inputs
DQ0 - DQ7	Data Inputs/Outputs
CE#	Chip Enable Inputs
WE#	Write Enable Input
OE#	Output Enable Input
Vcc	Power Supply
Vss	Ground
NC	No Connection

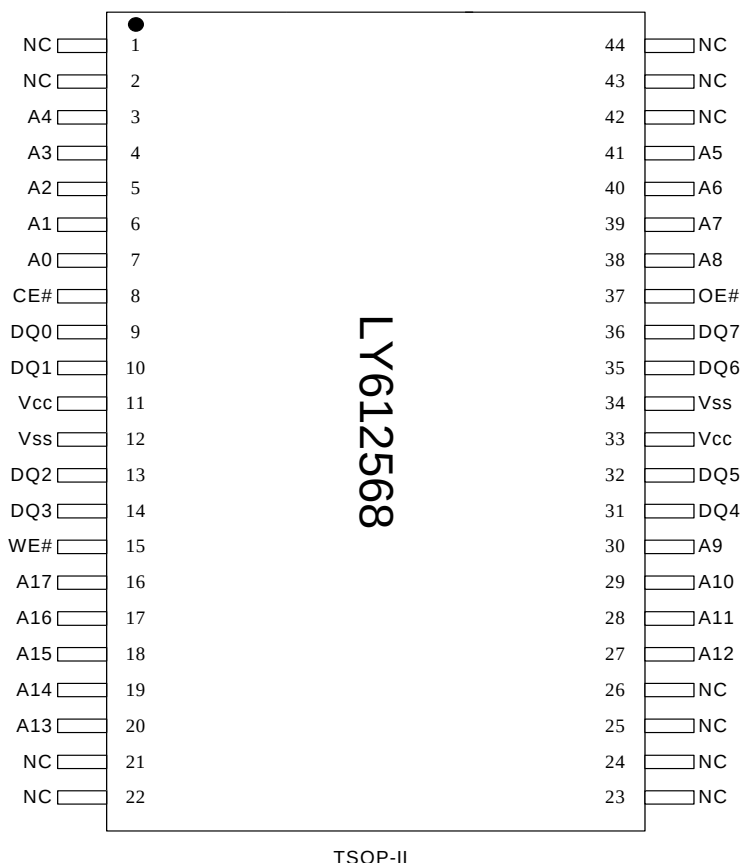


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PIN CONFIGURATION



TSOP-II

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ABSOLUTE MAXIMUM RATINGS*

PARAMETER	SYMBOL	RATING	UNIT
Voltage on Vcc relative to Vss	V _{T1}	-0.5 to 6.5	V
Voltage on any other pin relative to Vss	V _{T2}	-0.5 to Vcc+0.5	V
Operating Temperature	T _A	0 to 70(C grade)	°C
		-20 to 80(E grade)	
		-40 to 85(I grade)	
Storage Temperature	T _{STG}	-65 to 150	°C
Power Dissipation	P _D	1	W
DC Output Current	I _{OUT}	50	mA

*Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to the absolute maximum rating conditions for extended period may affect device reliability.



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TRUTH TABLE

MODE	CE#	OE#	WE#	I/O OPERATION	SUPPLY CURRENT
Standby	H	X	X	High-Z	I _{SB1}
Output Disable	L	H	H	High-Z	I _{CC}
Read	L	L	H	DOUT	I _{CC}
Write	L	X	L	DIN	I _{CC}

Note: H = V_{IH}, L = V_{IL}, X = Don't care.

DC ELECTRICAL CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP. ⁴	MAX.	UNIT
Supply Voltage	V _{CC}		4.5	5.0	5.5	V
Input High Voltage	V _{IH} ¹		2.2	-	V _{CC} +0.3	V
Input Low Voltage	V _{IL} ²		- 0.3	-	0.8	V
Input Leakage Current	I _{LI}	V _{CC} ≥ V _{IN} ≥ V _{SS}	- 1	-	1	μA
Output Leakage Current	I _{LO}	V _{CC} ≥ V _{OUT} ≥ V _{SS} , Output Disabled	- 1	-	1	μA
Output High Voltage	V _{OH}	I _{OH} = -4mA	2.4	-	-	V
Output Low Voltage	V _{OL}	I _{OL} = 8mA	-	-	0.4	V
Average Operating Power supply Current	I _{CC}	Cycle time = Min.	-15	-	100	mA
		CE# = V _{IL} , I _{I/O} = 0mA	-20	-	80	mA
		Other pins at V _{IH} or V _{IL}	-25	-	75	mA
Standby Power Supply Current	I _{SB1}	CE# ≥ V _{CC} - 0.2V Other pins at 0.2V or V _{CC} -0.2V	-	0.1	3 ⁵	mA

Notes:

- V_{IH}(max) = V_{CC} + 3.0V for pulse width less than 10ns.
- V_{IL}(min) = V_{SS} - 3.0V for pulse width less than 10ns.
- Over/Undershoot specifications are characterized, not 100% tested.
- Typical values are included for reference only and are not guaranteed or tested.
- Typical values are measured at V_{CC} = V_{CC}(TYP.) and T_A = 25°C
- 1mA for special request

CAPACITANCE (T_A = 25°C, f = 1.0MHz)

PARAMETER	SYMBOL	MIN.	MAX	UNIT
Input Capacitance	C _{IN}	-	8	pF
Input/Output Capacitance	C _{I/O}	-	10	pF

Note : These parameters are guaranteed by device characterization, but not production tested.

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5V 256K X 8 BIT HIGH SPEED CMOS SRAM**AC TEST CONDITIONS**

Input Pulse Levels	0.2V to V _{CC} - 0.2V
Input Rise and Fall Times	3ns
Input and Output Timing Reference Levels	1.5V
Output Load	C _L = 30pF + 1TTL, I _{OH} /I _{OL} = -8mA/16mA

AC ELECTRICAL CHARACTERISTICS**(1) READ CYCLE**

PARAMETER	SYM.	LY612568-15		LY612568-20		LY612568-25		UNIT
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
Read Cycle Time	t _{RC}	15	-	20	-	25	-	ns
Address Access Time	t _{AA}	-	15	-	20	-	25	ns
Chip Enable Access Time	t _{ACE}	-	15	-	20	-	25	ns
Output Enable Access Time	t _{OE}	-	7	-	8	-	9	ns
Chip Enable to Output in Low-Z	t _{CLZ} *	4	-	4	-	4	-	ns
Output Enable to Output in Low-Z	t _{OLZ} *	0	-	0	-	0	-	ns
Chip Disable to Output in High-Z	t _{CHZ} *	-	7	-	8	-	9	ns
Output Disable to Output in High-Z	t _{OHZ} *	-	7	-	8	-	9	ns
Output Hold from Address Change	t _{OH}	3	-	3	-	3	-	ns

(2) WRITE CYCLE

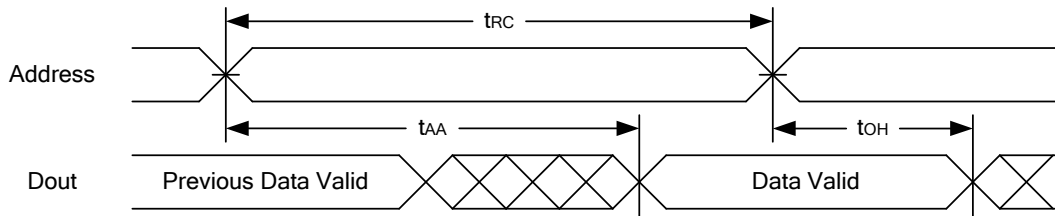
PARAMETER	SYM.	LY612568-15		LY612568-20		LY612568-25		UNIT
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
Write Cycle Time	t _{WC}	15	-	20	-	25	-	ns
Address Valid to End of Write	t _{AW}	12	-	16	-	20	-	ns
Chip Enable to End of Write	t _{CW}	12	-	16	-	20	-	ns
Address Set-up Time	t _{AS}	0	-	0	-	0	-	ns
Write Pulse Width	t _{WP}	10	-	11	-	12	-	ns
Write Recovery Time	t _{WR}	0	-	0	-	0	-	ns
Data to Write Time Overlap	t _{DW}	8	-	9	-	10	-	ns
Data Hold from End of Write Time	t _{DH}	0	-	0	-	0	-	ns
Output Active from End of Write	t _{OW} *	4	-	5	-	6	-	ns
Write to Output in High-Z	t _{WHZ} *	-	8	-	9	-	10	ns

*These parameters are guaranteed by device characterization, but not production tested.

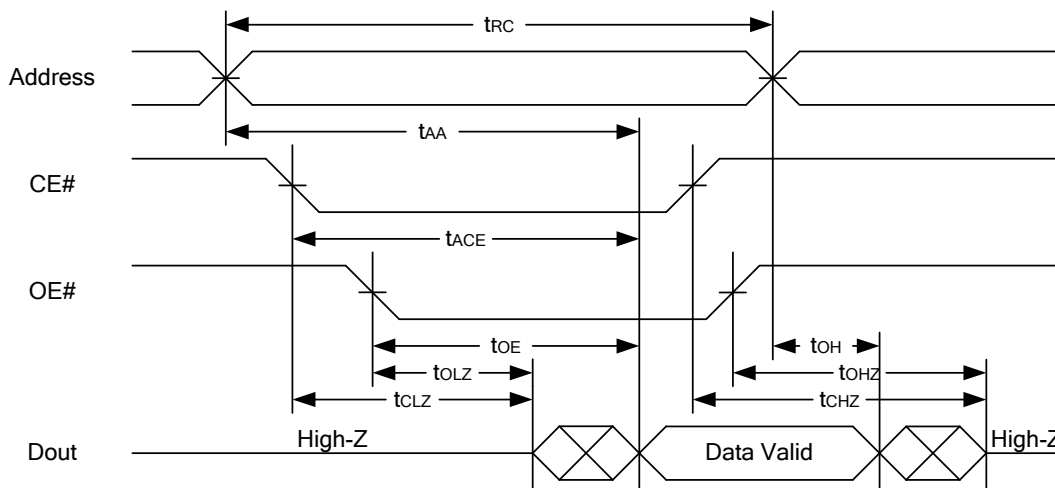


TIMING WAVEFORMS

READ CYCLE 1 (Address Controlled) (1,2)



READ CYCLE 2 (CE# and OE# Controlled) (1,3,4,5)

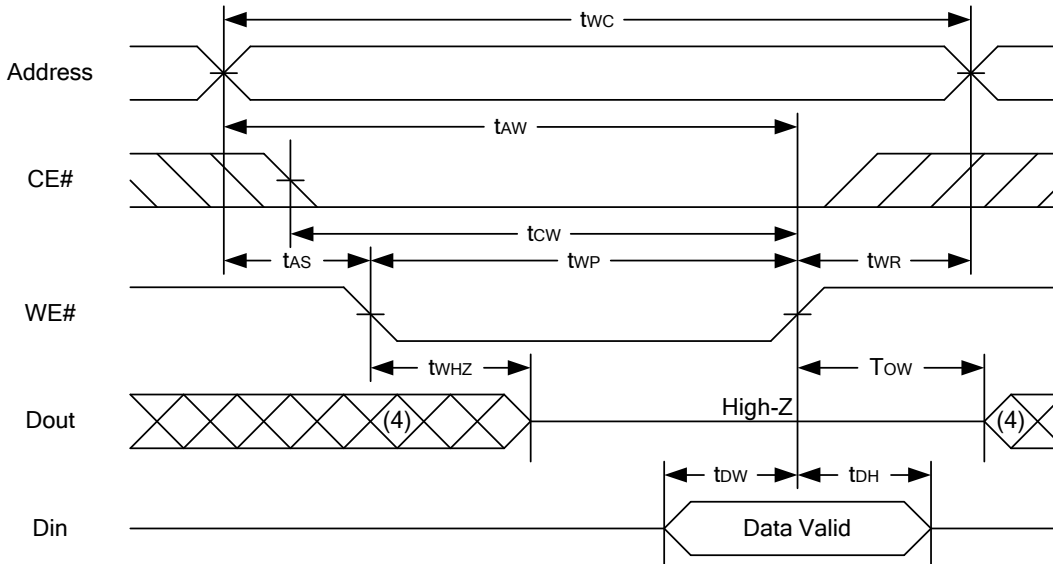


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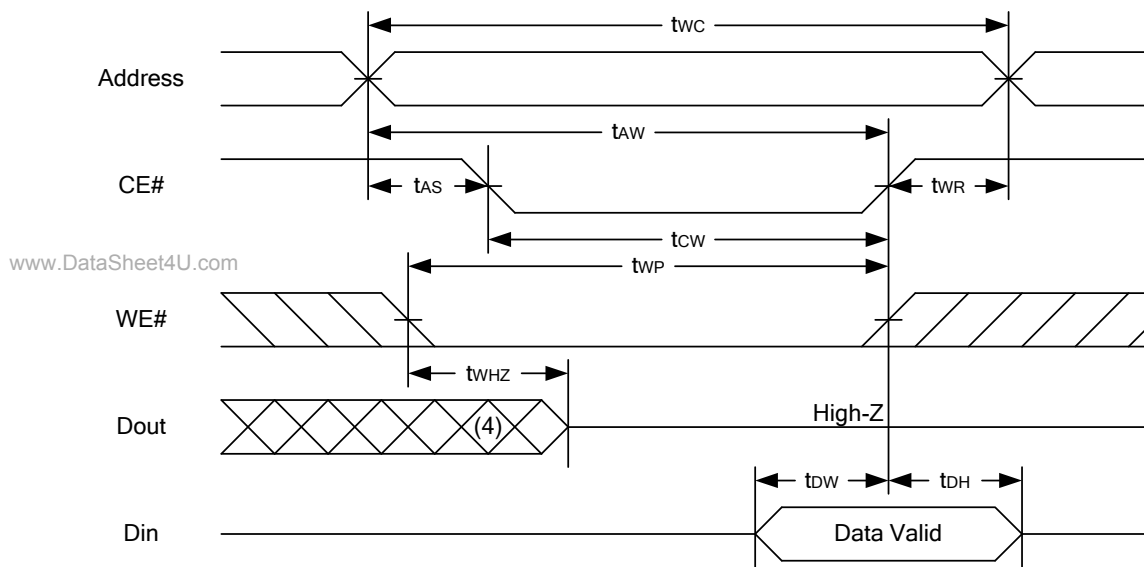
Notes :

1. WE# is high for read cycle.
2. Device is continuously selected OE# = low, CE# = low.
3. Address must be valid prior to or coincident with CE# = low; otherwise t_{AA} is the limiting parameter.
4. t_{CLZ} , t_{OLZ} , t_{CHZ} and t_{OHZ} are specified with $C_L = 5pF$. Transition is measured $\pm 500mV$ from steady state.
5. At any given temperature and voltage condition, t_{CHZ} is less than t_{CLZ} , t_{OHZ} is less than t_{OLZ} .

WRITE CYCLE 1 (WE# Controlled) (1,2,3,5,6)



WRITE CYCLE 2 (CE# Controlled) (1,2,5,6)



Notes :

1. WE#, CE# must be high during all address transitions.
2. A write occurs during the overlap of a low CE#, low WE#.
3. During a WE# controlled write cycle with OE# low, twp must be greater than twhz + tdw to allow the drivers to turn off and data to be placed on the bus.
4. During this period, I/O pins are in the output state, and input signals must not be applied.
5. If the CE# low transition occurs simultaneously with or after WE# low transition, the outputs remain in a high impedance state.
6. tow and twhz are specified with CL = 5pF. Transition is measured $\pm 500\text{mV}$ from steady state.

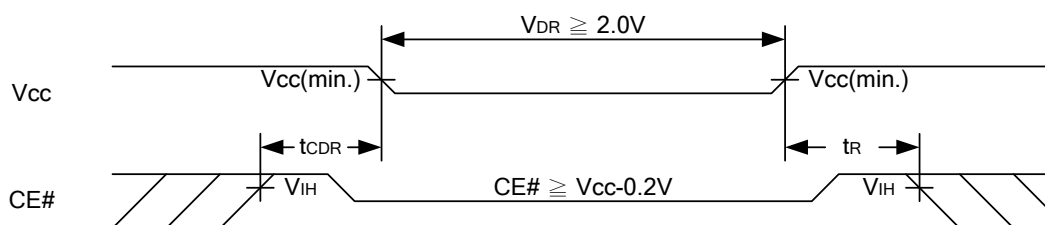


DATA RETENTION CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
V _{CC} for Data Retention	V _{DR}	CE# $\geq$ V _{CC} - 0.2V	2.0	-	5.5	V
Data Retention Current	I _{DR}	V _{CC} = 2.0V CE# $\geq$ V _{CC} - 0.2V Others at 0.2V or V _{CC} -0.2V	-	0.05	2	mA
Chip Disable to Data Retention Time	t _{CDR}	See Data Retention Waveforms (below)	0	-	-	ns
Recovery Time	t _R		t _{RC} *	-	-	ns

t_{RC}* = Read Cycle Time

DATA RETENTION WAVEFORM



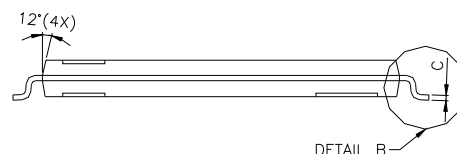
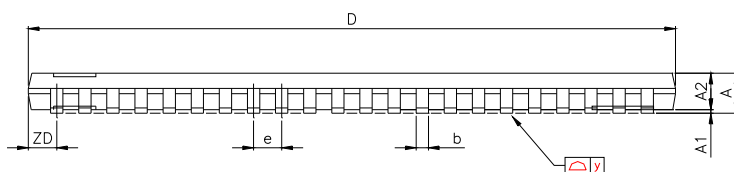
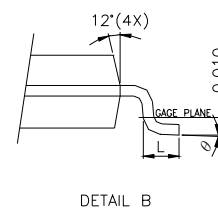
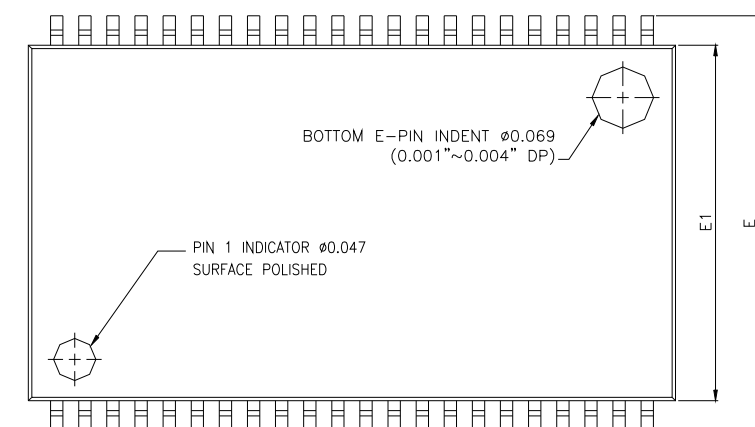
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PACKAGE OUTLINE DIMENSION

44-pin 400mil TSOP-II Package Outline Dimension



SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN MILS		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	-	-	1.20	-	-	47.2
A1	0.05	0.10	0.15	2.0	3.9	5.9
A2	0.95	1.00	1.05	37.4	39.4	41.3
b	0.30	-	0.45	11.8	-	17.7
c	0.12	-	0.21	4.7	-	8.3
D	18.212	18.415	18.618	717	725	733
E	11.506	11.760	12.014	453	463	473
E1	9.957	10.160	10.363	392	400	408
e	-	0.800	-	-	31.5	-
L	0.40	0.50	0.60	15.7	19.7	23.6
ZD	-	0.805	-	-	31.7	-
y	-	-	0.076	-	-	3
θ	0°	3°	6°	0°	3°	6°



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ORDERING INFORMATION

LY612568 U V - WW Y Z

Z : Packing Type

Blank : Tube or Tray

T : Tape Reel

Y : Temperature Range

Blank : (Commercial) 0°C ~ 70°C

E : (Extended) -20°C ~ +80°C

I : (Industrial) -40°C ~ +85°C

WW : Access Time(Speed)

V : Lead Information

L : Lead Free

U : Package Type

M : 44-pin 400 mil TSOP-II



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